

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method for inspecting semiconductor devices comprising:
setting, by using design information, an inspection condition;
inspecting the semiconductor device to detect defects with said inspection condition;
classifying said detected defects ~~and outputting information of classified defect with information on~~ according to whether said defect is on an optically transparent film or not;
revising said inspection condition by using data obtained by the inspecting;
and
inspecting another semiconductor device using said revised inspection condition.
2. (Previously presented) The method for inspecting semiconductor devices according to claim 1, wherein said inspection condition comprises information whether or not an area for inspection is in an area in which false alarms tend to occur.
3. (Canceled)
4. (Currently amended) A method for inspecting semiconductor devices comprising:
setting inspection conditions by using design information of a semiconductor device;
inspecting the semiconductor device to detect defects with said inspection conditions;
classifying defects detected by inspecting said semiconductor device according to whether said defect is on an optically transparent film or not; and

outputting results of the inspecting of the semiconductor devices by adding information on whether said detected defect is on an optically transparent film or not.

5. (Previously presented) The method for inspecting semiconductor devices according to claim 4, wherein said inspection conditions set at said setting comprises information whether or not an area to be inspected is in an area in which false alarms tend to occur.

6. (Previously presented) The method for inspecting semiconductor devices according to claim 4, further comprising revising said inspection conditions set at said setting so that only actual foreign matter is detected or a false alarm rate is less than a preset amount.

7. (Currently amended) A method for inspecting semiconductor devices comprising:

setting semiconductor device inspection conditions by using design information ~~and said inspection condition which differs in a comparing method and a threshold level based on a unit size of repeated patterns formed on a semiconductor device;~~

detecting defects by inspecting semiconductor devices using said set inspection conditions with an optical inspection tool;

classifying defects detected at said detecting according to whether said defect is on an optically transparent film or not; and

outputting a result of said detecting by adding information on whether or not said detected defect is possible to review by SEM based on said classifying.

8. (Original) The method for inspecting semiconductor devices according to claim 7, wherein images of said classified defects are displayed on a screen.

9. (Canceled)

10. (Previously presented) The method for inspecting semiconductor devices according to claim 7, further comprising revising said set inspection condition by using information of said classified defects.

11.-13. (Canceled)

14. (Currently amended) A method for inspecting a semiconductor device comprising:

setting inspection conditions for a semiconductor device using design information;

inspecting said semiconductor device under said set inspection conditions by using an optical inspection tool; and

classifying defects detected at said inspecting according to whether said defect is on an optically transparent film or not,

wherein said classifying comprises providing information on whether said detected defects are on an optically transparent film or optically non-transparent film.

15. (Previously presented) The method of claim 14 further comprising revising said inspection conditions set by using said design information.

16.-20. (Canceled)